ABSTRACT OF THE DISCLOSURE

There is provided an apparatus for spin-coating a semiconductor substrate, including (a) a rotary table rotatable in opposite directions, (b) a nozzle dropping coating material onto a semiconductor substrate lying on the rotary table, (c) an electrode having a ring-shaped cross-section and disposed around the rotary table, and (d) a power source applying a voltage to the electrode, the voltage having an electric polarity opposite to an electric polarity of the coating material. Coating material dropped onto the semiconductor substrate is attracted to an electric field generated by the electrode around the semiconductor substrate. Hence, the coating material is not concentrated around a center of the semiconductor substrate, but is facilitated to uniformly spread over the semiconductor substrate, ensuring formation of a coating layer having a uniform thickness.